Silicon N-Channel MOS FET

HITACHI

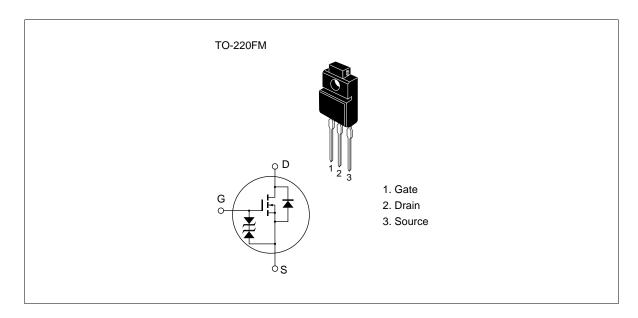
Application

High speed power switching

Features

- Low on-resistance
- High speed switching
- Low drive current
- · No secondary breakdown
- Suitable for switching regulator and DC-DC converter

Outline





Absolute Maximum Ratings ($Ta = 25^{\circ}C$)

Item		Symbol	Ratings	Unit
Drain to source voltage	2SK1626	$V_{ exttt{DSS}}$	450	V
	2SK1627		500	<u></u>
Gate to source voltage		V_{GSS}	±30	V
Drain current		I _D	5	А
Drain peak current		l _{D(pulse)} *1	20	А
Body to drain diode reverse drain current		I _{DR}	5	А
Channel dissipation		Pch*2	35	W
Channel temperature		Tch	150	°C
Storage temperature		Tstg	-55 to +150	°C

Note 1. PW \leq 10 μ s, duty cycle \leq 1%

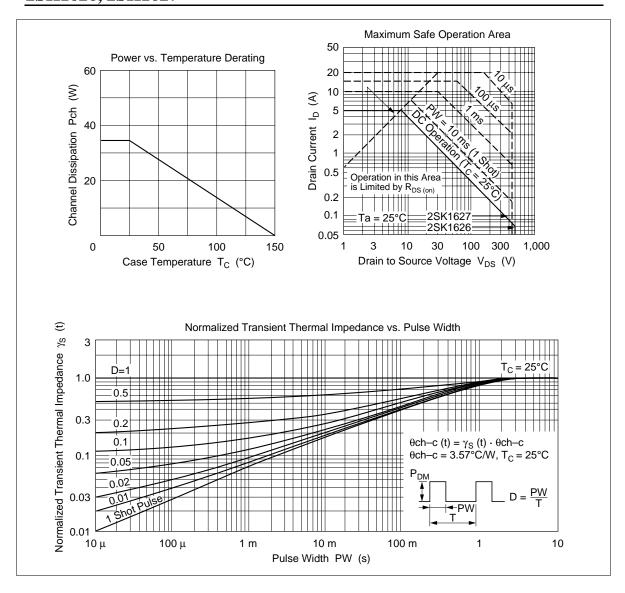
2. Value at $T_c = 25^{\circ}C$

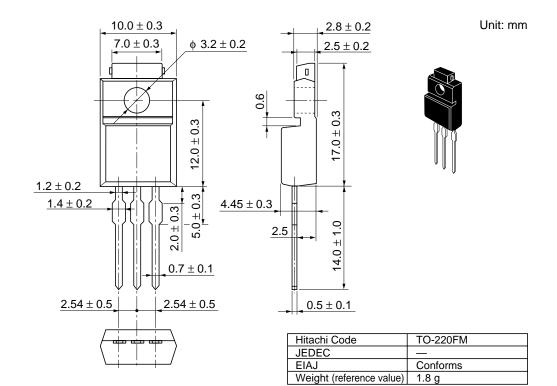
Electrical Characteristics ($Ta = 25^{\circ}C$)

Item		Symbol	Min	Тур	Max	Unit	Test conditions
Drain to source	2SK1626	$V_{(BR)DSS}$	450	_	_	V	$I_D = 10 \text{ mA}, V_{GS} = 0$
breakdown voltage	2SK1627	-	500	_			
Gate to source breakdown voltage		$V_{(BR)GSS}$	±30	_	_	V	$I_{G} = \pm 100 \ \mu A, \ V_{DS} = 0$
Gate to source leak current		I _{GSS}	_	_	±10	μΑ	$V_{GS} = \pm 25 \text{ V}, V_{DS} = 0$
Zero gate voltage	2SK1626	I _{DSS}	_	_	250	μΑ	$V_{DS} = 360 \text{ V}, V_{GS} = 0$
drain current	2SK1627	-					$V_{DS} = 400 \text{ V}, V_{GS} = 0$
Gate to source cutoff voltage		$V_{GS(off)}$	2.0	_	3.0	V	$I_{D} = 1 \text{ mA}, V_{DS} = 10 \text{ V}$
Static Drain to source	2SK1626	R _{DS(on)}	_	1.0	1.4	Ω	$I_D = 2.5 \text{ A}, V_{GS} = 10 \text{ V}^{*1}$
on state resistance	2SK1627	-	_	1.2	1.5	-	
Forward transfer admittance		yfs	2.5	4.0	_	S	$I_D = 2.5 \text{ A}, V_{DS} = 10 \text{ V}^{*1}$
Input capacitance		Ciss	_	640	_	pF	$V_{DS} = 10 \text{ V}, V_{GS} = 0,$
Output capacitance		Coss	_	160	_	pF	f = 1 MHz
Reverse transfer capacitance		Crss	_	20	_	pF	
Turn-on delay time		$t_{\text{d(on)}}$	_	10	_	ns	$I_D = 2.5 \text{ A}, V_{GS} = 10 \text{ V},$
Rise time		t _r	_	25	_	ns	$R_L = 12 \Omega$
Turn-off delay time		t _{d(off)}	_	50	_	ns	-
Fall time		t _f	_	30	_	ns	-
Body to drain diode forward voltage		V_{DF}		0.95		V	$I_F = 5 A, V_{GS} = 0$
Body to drain diode re recovery time	verse	t _{rr}	_	300	_	ns	$I_F = 5 \text{ A}, V_{GS} = 0,$ $di_F/dt = 100 \text{ A}/\mu\text{s}$

Note 1. Pulse test

See characteristic curves of 2SK1155, 2SK1156.





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Semiconductor & Integrated Circuits.

Nippon Bldg., 2-6-2, Öhte-machi, Chiyoda-ku, Tokyo 100-0004, Japan Tel: Tokyo (03) 3270-2111 Fax: (03) 3270-5109

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For further information write to:

Hitachi Semiconductor (America) Inc. 179 East Tasman Drive. San Jose, CA 95134 Tel: <1> (408) 433-1990 Fax: <1>(408) 433-0223 Hitachi Europe GmbH Electronic components Group D-85622 Feldkirchen, Munich Germany

Tel: <49> (89) 9 9180-0 Fax: <49> (89) 9 29 30 00 Hitachi Europe Ltd.

Electronic Components Group. Whitebrook Park Lower Cookham Road Maidenhead

Berkshire SL6 8YA, United Kingdom Tel: <44> (1628) 585000 Fax: <44> (1628) 778322

Hitachi Asia Pte. Ltd. 16 Collyer Quay #20-00 Hitachi Tower Singapore 049318 Tel: 535-2100 Fax: 535-1533

Hitachi Asia Ltd. Taipei Branch Office 3F, Hung Kuo Building. No.167, Tun-Hwa North Road, Taipei (105) Tel: <886> (2) 2718-3666 Fax: <886> (2) 2718-8180

Hitachi Asia (Hong Kong) Ltd. Group III (Electronic Components) 7/F., North Tower, World Finance Centre, Harbour City, Canton Road, Tsim Sha Tsui, Kowloon, Hong Kong Tel: <852> (2) 735 9218 Fax: <852> (2) 730 0281

Telex: 40815 HITEC HX

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